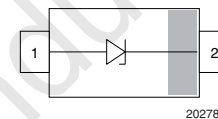
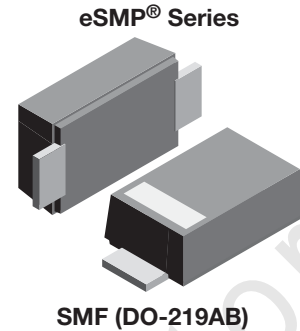


### FEATURES

- 200 W peak pulse power capability with a 10/1000  $\mu$ s waveform, repetition rate (duty cycle): 0.01 %
- Low-profile package
- Wave and reflow solderable
- ESD immunity acc. IEC 61000-4-2  
 $\pm$  30 kV contact discharge  
 $\pm$  30 kV air discharge
- ESD capability according to AEC-Q101:  
human body model: class H3B: > 8 kV
- Low incremental surge resistance, excellent clamping capability
- “Low-Noise” technology - very fast response time
- AEC-Q101 qualified available



<b>ORDERING INFORMATION</b>							
PART NUMBER (EXAMPLE)	ENVIRONMENTAL AND QUALITY CODE			PACKAGING CODE		ORDERING CODE (EXAMPLE)	
	AEC-Q101 QUALIFIED	RoHS-COMPLIANT + LEAD (Pb)-FREE TERMINATIONS		TIN PLATED	3K PER 7" REEL (8 mm TAPE), MOQ = 30K		10K PER 13" REEL (8 mm TAPE), MOQ = 50K
		STANDARD	HALOGEN-FREE				
SMF5V0A-		E		3	-08		SMF5V0A-E3-08
SMF5V0A-			M	3	-08		SMF5V0A-M3-08
SMF5V0A-	H	E		3	-08		SMF5V0A-HE3-08
SMF5V0A-	H		M	3	-08		SMF5V0A-HM3-08
SMF5V0A-		E		3		-18	SMF5V0A-E3-18
SMF5V0A-			M	3		-18	SMF5V0A-M3-18
SMF5V0A-	H	E		3		-18	SMF5V0A-HE3-18
SMF5V0A-	H		M	3		-18	SMF5V0A-HM3-18

<b>PACKAGE DATA</b>									
PACKAGE NAME	MOLDING COMPOUND	WEIGHT (mg)	HEIGHT MAX. (mm)	LENGTH MAX. (mm)	WIDTH MAX. (mm)	MOLDING COMPOUND FLAMMABILITY RATING	MOISTURE SENSITIVITY LEVEL	WHISKER TEST ACC. JESD 201	SOLDERING CONDITIONS
SMF (DO-219AB)	Standard Halogen-free	15	1.08	3.9	1.9	UL 94 V-0	MSL level 1 (acc. J-STD-020)	class 2	Peak temperature max. 260 °C

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)				
PARAMETER	TEST CONDITIONS	SYMBOL	VALUE	UNIT
Peak pulse current	$t_p = 10/1000\text{ }\mu\text{s}$ waveform	$I_{PPM}$	see "Electrical Characteristics"	A
Peak pulse power	$t_p = 8/20\text{ }\mu\text{s}$ waveform acc. IEC 61000-4-5	$P_{PP}$	1000	W
	$t_p = 10/1000\text{ }\mu\text{s}$ waveform		200	W
Peak forward surge current	8.3 ms single half sine-wave	$I_{FSM}$	50	A
ESD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses	$V_{ESD}$	$\pm 30$	kV
	Air discharge acc. IEC 61000-4-2; 10 pulses		$\pm 30$	kV
Thermal resistance	Mounted on epoxy glass PCB with 3 mm x 3 mm, Cu pads ( $\geq 40\text{ }\mu\text{m}$ thick)	$R_{thJA}$	180	K/W
Forward clamping voltage	$I_F = 50\text{A}$ , $t_p = 400\text{ }\mu\text{s}$	$V_F$	2.5	V
Junction temperature		$T_J$	175	$^{\circ}\text{C}$
Storage temperature range		$T_{stg}$	-65 to +175	$^{\circ}\text{C}$
Operating temperature range		$T_{op}$	-65 to +175	$^{\circ}\text{C}$

<b>ELECTRICAL CHARACTERISTICS</b> ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)										
PART NUMBER	TYPE CODE		REVERSE BREAKDOWN VOLTAGE at $I_R$ , $t_p = 5\text{ ms}$	TEST CURRENT	STAND-OFF VOLTAGE	MAXIMUM REVERSE CURRENT at $V_{RWM}$	MAXIMUM PEAK PULSE CURRENT $t_p = 10/1000\text{ }\mu\text{s}$	MAXIMUM REVERSE CLAMPING VOLTAGE at $I_{PPM}$	TYPICAL CAP. at $V_R = 0\text{ V}$ , $f = 1\text{ MHz}$	PROTECTION PATHS
	STD.	HALOGEN-FREE	$V_{BR\text{ MIN.}}$ (V)	$I_R$ (mA)	$V_{RWM}$ (V)	$I_R$ ( $\mu\text{A}$ )	$I_{PPM}$ (A)	$V_C\text{ MAX.}$ (V)	$C_D\text{ TYP.}$ (pF)	$N_{channel}$
SMF5V0A	AE	NE	6.40	10	5	5	21.7	9.2	1120	1
SMF6V0A	AG	NG	6.67	10	6	26	19.4	10.3	1063	1
SMF6V5A	AK	NK	7.22	10	6.5	20	17.9	11.2	938	1
SMF7V0A	AM	NM	7.78	10	7	3	16.7	12	843	1
SMF7V5A	AP	NP	8.33	1	7.5	0.1	15.5	12.9	773	1
SMF8V0A	AR	NR	8.89	1	8	0.1	14.7	13.6	706	1
SMF8V5A	AT	NT	9.44	1	8.5	0.1	13.9	14.4	674	1
SMF9V0A	AV	NV	10	1	9	0.1	13.5	15.4	640	1
SMF10A	AX	NX	11.1	1	10	0.1	11.8	17	562	1
SMF11A	AZ	NZ	12.2	1	11	0.1	11	18.2	509	1
SMF12A	BE	OE	13.3	1	12	0.1	10.1	19.9	483	1
SMF13A	BG	OG	14.4	1	13	0.1	9.3	21.5	423	1
SMF14A	BK	OK	15.6	1	14	0.1	8.6	23.2	392	1
SMF15A	BM	OM	16.7	1	15	0.1	8.2	24.4	367	1
SMF16A	BP	OP	17.8	1	16	0.1	7.7	26	343	1
SMF17A	BR	OR	18.9	1	17	0.1	7.2	27.6	324	1
SMF18A	BT	OT	20	1	18	0.1	6.8	29.2	320	1
SMF20A	BV	OV	22.2	1	20	0.1	6.2	32.4	283	1
SMF22A	BX	OX	24.4	1	22	0.1	5.6	35.5	271	1
SMF24A	BZ	OZ	26.7	1	24	0.1	5.1	38.9	244	1
SMF26A	CE	PE	28.9	1	26	0.1	4.8	42.1	230	1
SMF28A	CG	PG	31.1	1	28	0.1	4.4	45.4	227	1
SMF30A	CK	PK	33.3	1	30	0.1	4.1	48.4	207	1
SMF33A	CM	PM	36.7	1	33	0.1	3.8	53.3	198	1
SMF36A	CP	PP	40	1	36	0.1	3.4	58.1	178	1
SMF40A	CR	PR	44.4	1	40	0.1	3.1	64.5	172	1
SMF43A	CT	PT	47.8	1	43	0.1	2.9	69.4	165	1
SMF45A	CV	PV	50	1	45	0.1	2.8	72.7	162	1
SMF48A	CX	PX	53.3	1	48	0.1	2.6	77.4	161	1
SMF51A	CZ	PZ	56.7	1	51	0.1	2.4	82.4	151	1
SMF54A	CA	PA	60	1	54	0.1	2.25	88	148	1
SMF58A	CC	PC	64.4	1	58	0.1	2.1	95	144	1

**TYPICAL CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

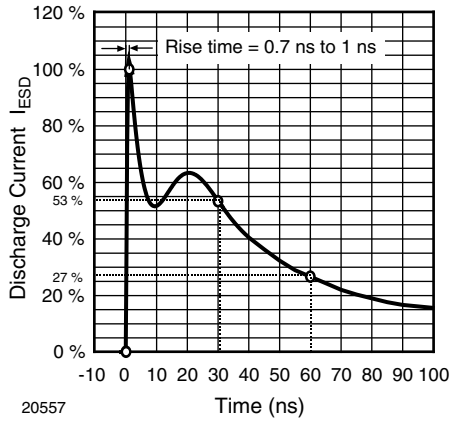


Fig. 1 - ESD Discharge Current Wave Form acc. IEC 61000-4-2 (330  $\Omega$ /150pF)

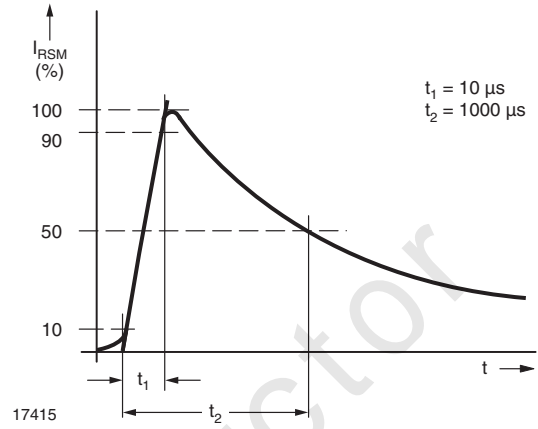


Fig. 4 - Pulse Waveform

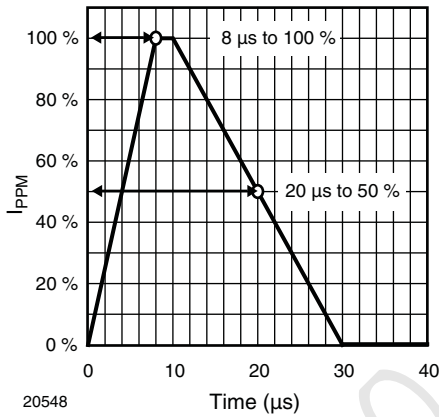


Fig. 2 - 8/20  $\mu\text{s}$  Peak Pulse Current Wave Form acc. IEC 61000-4-5

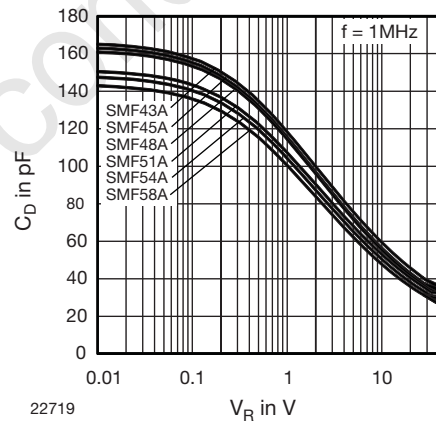


Fig. 5 - Typical Capacitance  $C_D$  vs. Reverse Voltage  $V_R$

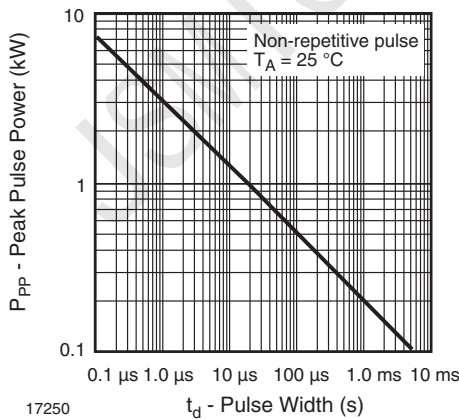


Fig. 3 - Peak Pulse Power Rating

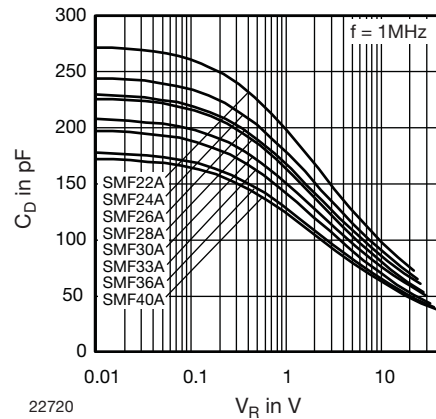


Fig. 6 - Typical Capacitance  $C_D$  vs. Reverse Voltage  $V_R$

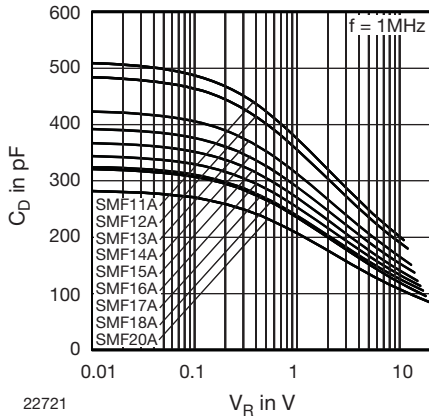


Fig. 7 - Typical Capacitance  $C_D$  vs. Reverse Voltage  $V_R$

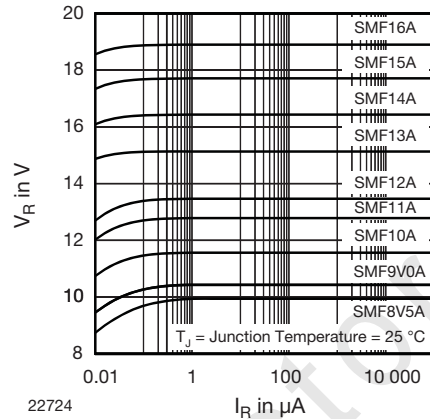


Fig. 10 - Typical Reverse Voltage  $V_R$  vs. Reverse Current  $I_R$

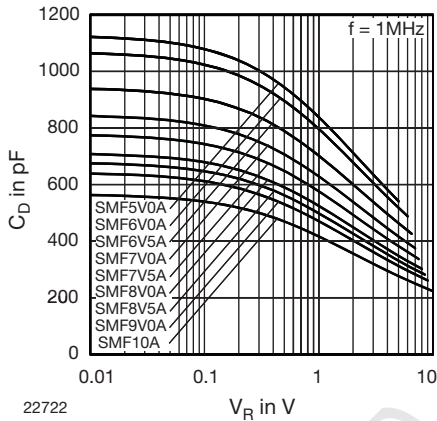


Fig. 8 - Typical Capacitance  $C_D$  vs. Reverse Voltage  $V_R$

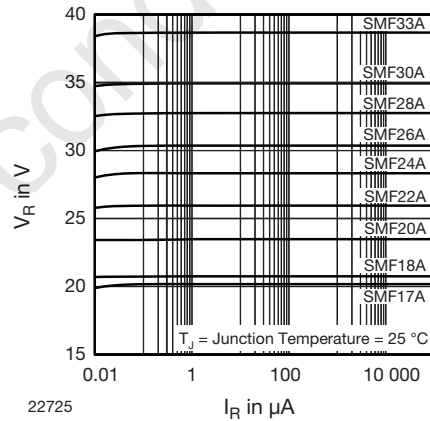


Fig. 11 - Typical Reverse Voltage  $V_R$  vs. Reverse Current  $I_R$

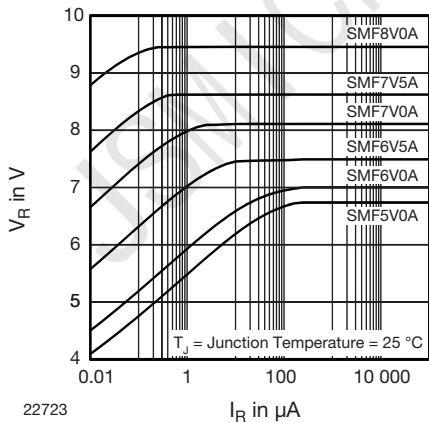


Fig. 9 - Typical Reverse Voltage  $V_R$  vs. Reverse Current  $I_R$

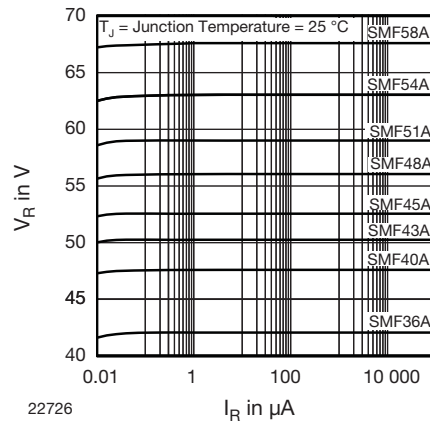
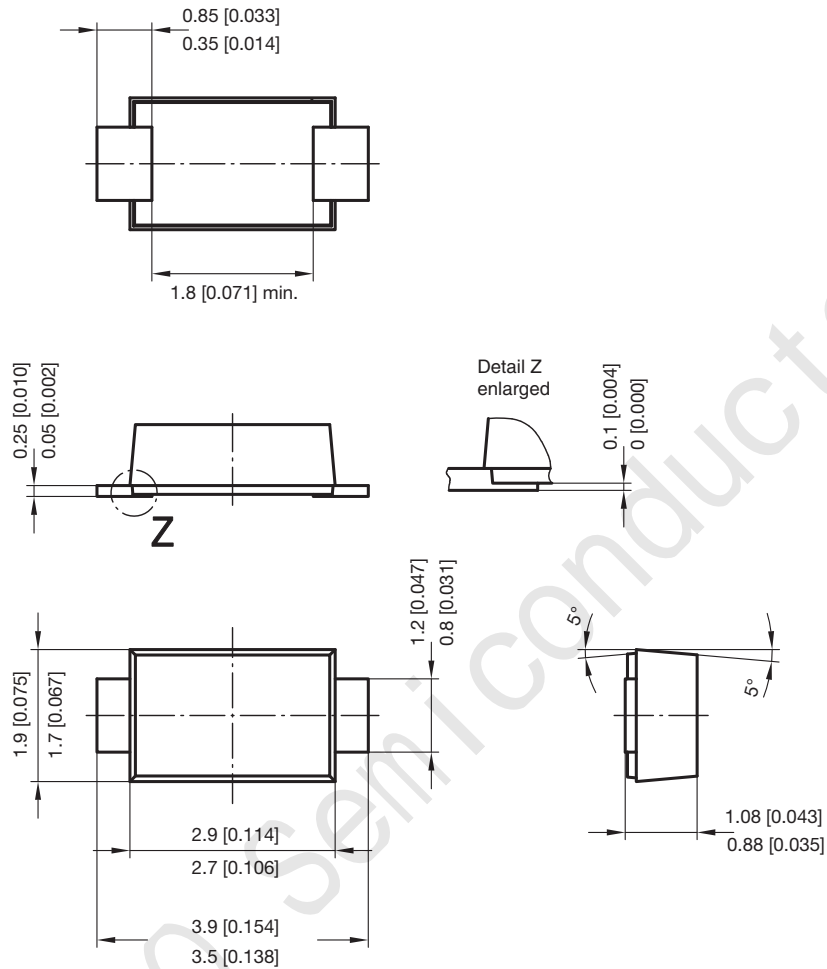


Fig. 12 - Typical Reverse Voltage  $V_R$  vs. Reverse Current  $I_R$

**PACKAGE DIMENSIONS** in millimeters (inches): **SMF (DO-219AB)**


foot print recommendation:

Reflow soldering

